

System: SRMS

Subsystem: ELECTRICAL SUB-SYSTEM

Assembly Desc: Servo Power Amplifier

Part Number(s): 51140F1177-3 51140F1177-5

Items:

Function: Central Processing Unit Assembly

Provides hardware and software necessary to implement servo control loops, control operation of the Analog I/F, Digital I/F and MDA boards and communicate with the MCIU. Provides PLL and frame sync BITE as well as a hardware watchdog timer to monitor health of microcomputer itself.

Motor Drive Amplifier Assembly

Provides motor voltage based on demand from tachometer electronics. Commutates the motor drive voltage. Provides hardware current limiting, brake drive, direct drive functions and enables backup drive. Provides BITE circuits and BITE verification for MDA.

Analog Interface Assembly

Provides Tachometer excitation, SCU signal filtering, Phase Locked Loop and tachometer counter circuits to provide measured motor speed data to Inner and outer rate loops. Provides analog to digital conversion of MDA buck output voltage, EPC +5V and reference voltages for BITE.

Filter Board Assembly

Filters 28V to SPA. Filters secondary voltages to position encoder, commutator and tachometer SCU. Provides backup relay to switch motor to backup drive.

Digital Interface Assembly

Receives and loads command data to CPU. Generates position encoder clock and syno signals, processes position encoder data and external flags and assembles return data for transmission to MCIU.

Failure Mode: EPC shuts down.

H/W Func. Screen Failures

Criticality: 2 1R

Mission Phase: Orbit

Cause(s): Analog Interface Assembly
Central Processing Unit Assembly
Digital Interface Assembly

Loss of EPC secondary voltages.
EPC +5VDC supply rail shorted.
EPC +10V supply fails shorted to ground.
Loss of EPC supply voltages.

Filter Board Assembly

Loss of +28VDC output to MDA and EPC.
Loss of EPC secondary voltages.

Motor Drive Amplifier Assembly

Loss of +28VDC output to MDA and EPC.
Loss of EPC current limiting.
Loss of EPC Feedback Voltage.
Loss of EPC supply voltages.
Series FET fails permanently on.

Failure effect on unit/end item:

All EPC outputs to SPA, Commutator and Position Encoder are lost. SPA shuts down. SPA fuse may be blown. Loss of computer supported and direct drive modes. All command and return data words are zero for failed joint and joints towards wrist. All command data words returned to MCIU are zero.

Worst Case: Unexpected motion. Free joint. Autobrakes.

Redundant Paths: Autobrakes (to Safe the System).

Backup Drive and End Effector Manual mode.

Retention Rationale

Design:

Discrete semiconductor devices are specified to at least the TX level of MIL-S-19500. Samples of all procured lots/date codes are subjected to destructive physical analysis (DPA) to verify the integrity of the manufacturing processes. Particle Impact Noise Detection (PIND) screening is performed on microcircuits, transistor and diodes that are mounted in a package with an internal cavity construction. The purpose of the test is to detect loose particles in the package, usually resulting from the assembly process. Device stress levels are derated in accordance with SPAR-RMS-PA.003 and verified by design review.

Opto-isolators are subjected to the same quality and application controls as applied to discrete semiconductors.

Resistors and capacitors used in the design are selected from established reliability (ER) types. Life expectancy is increased by ensuring that all allowable stress levels are derated in accordance with SPAR-RMS-PA.003. All ceramic and electrolytic capacitors are routinely subjected to radiographic inspection in accordance with the requirements of MSFC-STD-355.

Transformers and inductors are designed specifically for the application. These are toroid-wound and utilize a ferrite core material. Choice of wire size and of insulation materials ensure that the derating requirements of SPAR-RMS-PA.003 are met.

Comparators and operational amplifiers are standard linear integrated circuits with mature manufacturing technology. Application constraints are in accordance with SPAR-RMS-PA.003.

The SPA board is fabricated using Surface Mount Technology (SMT). This is a PWB assembly technology in which the components are soldered to the solder pads on the surface of the PWB. The significant advantage of this technology is to enable the parts on the board to be more densely packed, to reduce the overall volume and weight of the assembly.

The assembly process is highly automated. The parts are mounted on the boards using a computer controlled "pick and place" machine. The subsequent soldering operation is performed using a belt furnace, in which the time and temperature thermal profile that the PWB assembly is exposed to is tightly controlled and optimized to ensure proper part soldering attachment. The assembly is manufactured under documented procedures and quality controls. These controls are exercised throughout the assembly, inspection and testing of the unit. This inspection includes workmanship, component mounting, soldering, and conformal coating to ensure that it is in accordance with the NHB 5300 standards.

The SMT line used for the SPA PWB assembly has undergone a full qualification program, and assemblies produced on this line are used in other space programs.

The circuit board design has been reviewed to ensure adequate conductor width and separation and to confirm appropriate dimensions of solder pads and of component hold provisions. Parts mounting methods are controlled in accordance with MSFC-STD-154A, MSFC-STD-1 and SASO 2673751. These documents require approved mounting methods, stress relief and component security.

Test:

QUALIFICATION TESTS - The SPA is subjected to the following qualification testing:

VIBRATION: Each axis of the QM is subjected to Flight Acceptance Vibration Test (FAVT), Qualification Acceptance Vibration Test (QAVT), and Qualification Vibration Tests (QVT) in accordance with the SPA Vibration Test Procedure (826586). The level and duration for FAVT is as per Figure 6 and Table 2 of 826586; the level and duration for QAVT is as per Figure 7 and Table 2 of 826586; the level and duration for QVT is as per Figure 8 and Table 2 of 826586. At the end of the three successive random vibration test in each axis, both directions (+/-) of each of the axis is subjected to a shock pulse test as per Figure 9 of 826586.

THERMAL/VACUUM: QM TVAC Test is in accordance with Figure 5 of the SPA TVAC Test Procedure (826586), with full Functional/Parametric Test performed at levels of +60 degrees C and -36 degrees C, and non-operating at -54 degrees C. The Qualification vacuum levels during TVAC is 1×10^{-8} torr or less. The total test duration is 7 1/2 cycles. The QM SPA is subjected to a minimum of 1000 hours of life testing and 1000 power On-Off cycles.

EMC: The QM is subjected to EMC Testing (tests CE01/CE03, CE07, CS01, CS02, CS06, RE02, RS02, and RS03) in accordance with the SPA EMC test Procedure (826477) based on MIL-STD-461A.

UNIT FLIGHT ACCEPTANCE TESTS - The FM SPA is subjected to the following acceptance testing:

VIBRATION: FM Acceptance Vibration Test (AVT) in accordance with the SPA Vibration Test Procedure (826586), with level and duration as per Figure 6 and Table 2 of 826586.

THERMAL/VACUUM: FM TVAC Test is in accordance with Figure 6 of the SPA TVAC Test Procedure (826586), with levels of +49 degrees C and -25 degrees C for a duration of 1 1/2 cycles. The vacuum levels during Acceptance TVAC Test is 1×10^{-5} torr or less.

JOINT SRU TESTS - The SPA is tested as part of the joints (ambient and vibration tests only). The ambient ATP for the Shoulder Joint, Elbow Joint, and Wrist Joint are as per ATP.2001, ATP.2003, and ATP.2005 respectively. The vibration test for the Shoulder Joint, Elbow Joint, and Wrist Joint are as per ATP.2002, ATP.2004 and ATP.2006 respectively. Through wire function, continuity and electrical isolation tests are performed per TP.283.

MECHANICAL ARM REASSEMBLY - The SPA's/Joints undergo a mechanical arm integration stage where electrical checks are performed per TP.2007.

MECHANICAL ARM TESTING - The outgoing spill-arm is configured on the Strongback and the Manipulator Arm Checkout is performed per ATP.1932

FLIGHT CHECKOUT: PDRS DP5 Checkout (all vehicles) JSC 16997.

Inspection:

Units are manufactured under documented quality controls. These controls are exercised throughout design procurement, planning, receiving, processing, fabrication, assembly, testing and shipping of the units. Mandatory inspection points are employed at various stages of fabrication, assembly, and test. Government source inspection is invoked at various control levels.

EEE parts inspection is performed as required by SPAR-RMS-PA.003. Each EEE part is qualified at the part level to the requirements of the applicable specification. All EEE parts are 100% screened and burned-in, as a minimum, as required by SPAR-RMS-PA.003, by the supplier. DPA is performed as required by PA.003 on a randomly selected 5% of parts, maximum 5 pieces, minimum 3 pieces for each lot number/date code of parts received. All cavity devices are subjected to 100% PIND. Wire is procured to specification MIL-W-22759 or MIL-W-81381 and inspected and tested to NASA JSCM8080 Standard Number 95A.

Receiving inspection verifies that all parts received are as identified in the procurement documents, that no physical damage has occurred to parts during shipment, that the receiving documents provide adequate traceability information and screening data clearly identifies acceptable parts.

Parts are inspected throughout manufacture and assembly as appropriate to the manufacturing stage completed. These inspections include:

Printed circuit board inspection for track separation, damage and adequacy of plated through holes, component mounting inspection for correct soldering, wire looping, strapping, etc. Operators and inspectors are trained and certified to NASA NHB 6300.4(3A-1) Standard. Conformal coating inspection for adequate processing is performed using ultraviolet light techniques. P.C. Board installation inspection includes checks for correct board installation, alignment of boards, proper connector contact mating, wire routing, strapping of wires etc. Post P.C. Board installation inspection includes cleanliness and workmanship (Spar/government rep. mandatory inspection point).

Unit Pre-Acceptance Test Inspection, which includes an audit of lower tier inspection completion, as built configuration verification to as design etc (mandatory inspection point). A unit Test Readiness Review (TRR) which includes verification of test personnel, test documents, test equipment calibration/validation status and hardware configuration is convened by QA in conjunction with Engineering, Reliability, Configuration Control, Supplier as applicable, and the government representative, prior to the start of any formal testing (Acceptance or Qualification). Unit level Acceptance Testing (ATP) includes ambient performance, thermal and vibration testing (Spar/government rep. mandatory inspection point).

Integration of unit to Joint SRU - Inspections include grounding checks, connectors for bent or pushback contacts, visual, cleanliness, interconnect wiring and power up test to the appropriate Joint Inspection Test Procedure (ITP). Joint level Pre-Acceptance Test Inspection, includes an audit of lower tier inspection completion, as built configuration verification to as design etc. Joint level Acceptance Testing (ATP) includes ambient and vibration testing (Spar/government rep. mandatory inspection point).

Mechanical Arm Reassembly - the integration of mechanical arm subassemblies to form the assembled arm. Inspections are performed at each phase of integration which includes electrical checks, through wiring checks, wiring routing, interface connectors for bent or pushback contacts etc. Mechanical Arm Testing - Strongback and flat floor ambient performance test (Spar/government rep. mandatory inspection point).

OMRSD Offline: Power-up arm. Verify no ABE communication failures or BITE errors.

OMRSD Online Installation: None.

OMRSD Online Turnaround: Power-up arm. Verify no ABE communication failures or BITE errors.

Screen Failure: A: Pass
B: Pass
C: Pass

Crew Training: The crew will be trained to always observe whether the arm is responding properly to commands. If it isn't, apply brakes.

Crew Action: Select Back-up Drive. Use EE Manual Mode.

Operational Effect: Cannot use computer supported modes of operation: Autobrakes. Direct Drive and Backup available. EE auto mode is unavailable. Arm will not stop automatically if failure of the auto brakes system has previously occurred. Brakes can be applied manually.

Mission Constraints: Operate under various rates within approximately 10 ft of structure. The operator must be able to detect that the arm is responding properly to commands via window and/or CCTV views during all arm operations. Auto trajectories must be designed to come no closer than approximately 5 ft from structure.

Approvals:

Functional Group	Name	Position	Telephone	Date Signed	Status
Quality	Hiltz, Michael / SPAR-BRAMPTON	Systems Engineer	4634	06Mar98	Signed
	Molgaard, Lena / SPAR-BRAMPTON	Reliability Engineer	4690	06Mar99	Signed

SPAR - BRAMPTON (SSS)
9445 AIRPORT RD

Critical Items List

SRM

BRAMPTON ONTARIO L5S4J3

CIL Ref#: 3157

Revision: 0

FMEA Rev: 0

Program Management Office	Rice, Craig / SPAR-BRAMPTON	Technical Program Manager	4892	06Mar98	Signed
Subsystem Manager	Glenn, George / JSC-ER	RMS Subsystem Manager	(281) 483-1516	30Mar98	Signed
Technical Manager	Allison, Ron / JSC-MV6	RMS Project Engineer JSC	(713) 483-4072	09Apr98	Signed
SAFETY - MISSION ASSURANCE CORN, DAVID / JSC-NCL		RMS SYSTEM ENGINEER	(281) 483-3999	30 Apr 98	Signed